

I. Number	Hits	Search Text	DB	Time stamp
1	707311	ball or bump or solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
2	9546	pressure adj weld\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
3	879	(ball or bump or solder) and (pressure adj weld\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:24
4	841114	chip or die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:25
5	283	((ball or bump or solder) and (pressure adj weld\$4)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 07:39
6	3	"6553660"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:02
7	479	438/109.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:03
8	328	438/109.ccls. and (ball or bump or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:04
9	3	(438/109.ccls. and (ball or bump or solder)) and (pressure adj weld\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:03
10	325	(438/109.ccls. and (ball or bump or solder)) not ((438/109.ccls. and (ball or bump or solder)) and (pressure adj weld\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:09
11	2	("5973403").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:11
12	2970461	pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:11
13	0	("5973403").PN.) and pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:12
14	4	((("5696036") or ("20020045290")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/10 08:14

15	4	(("5696031") or ("20020045290")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/10/10 08:14
16	21	("4447857") "4567643" "4991000" "5228192" "5252857" "5291064" "5311059" "5323060" "5355283" "5399898" "5399903" "5422435" "5434745" "5436203" "5467253" "5468999" "5495398" "5502289" "5508561" "5514907" "5527740").PN.		2003/10/10 08:18
17	28	5696031.URPN.	USPAT	2003/10/10 08:21
18	28	5696031.URPN.	USPAT	2003/10/10 08:28